ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the s encompasse	ubstances es all lowe	within the r level mate	manufacture erials for wh	er listed iten nich the ma	m. Note: i nufacture	if the item is an as r has engineering	sembly with lower responsibility.
				Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information														
Company name* Comp			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2024-05-02			
Contact Name Title - Contact				I			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product En			t Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Rep			Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product			duct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	er Mfr Item Number		nber Mfr Item Name			Effective Dat	e Version]	Manufacturing Site		W	eight*	UOM	Unit Type
	MC74L0	MC74LCX86DR2G LOG CMOS		GATE EXCLSV OR		2024-05-02]	PH1		12	2.05	mg	Each
Manufacturing Proccess Informa	tion										·			
Terminal Plating / Grid Array Ma	Terminal Plating / Grid Array Material Terminal Base Alloy			J-STD-020 MSI	0 MSL Rating Peak Process Body Temperature Max T				re Max Ti	me at Peak 🕻	Temperatur	e Num	ber of Reflow Cyc	eles
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		seconds	3			
Comments														
evel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).										
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure		
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg		
Die Attach	4.44	mg	Supplier	Silver (Ag)	7440-22-4		3.33	mg		
			Supplier	Epoxy resins	129915-35-1		1.11	mg		
Lead Frame	69.62	mg	Supplier	Silver (Ag)	7440-22-4		0.7658	mg		
			Supplier	Zinc (Zn)	7440-66-6		0.1392	mg		
			Supplier	Iron (Fe)	7439-89-6		1.8101	mg		
			Supplier	Copper (Cu)	7440-50-8		66.9048	mg		
Mold Compound-Black	43.43	mg		Epoxy Phenol Resin	proprietary data		4.5601	mg		
			Supplier	Fused Silica (SiO2)	60676-86-0		38.8699	mg		
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg		
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg		

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted)